

# 74LVC125A-Q100

Quad buffer/line driver with 5 V tolerant input/outputs; 3-state

Rev. 1 — 4 April 2013

Product data sheet

## 1. General description

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The 74LVC125A-Q100 consists of four non-inverting buffers/line drivers with 3-state outputs (nY) that are controlled by the output enable input (nOE). A HIGH at nOE causes the outputs to assume a high-impedance OFF-state.

Inputs can be driven from either 3.3 V or 5 V devices. When disabled, up to 5.5 V can be applied to the outputs.

This product has been qualified to the Automotive Electronics Council (AEC) standard Q100 (Grade 1) and is suitable for use in automotive applications.

## 2. Features and benefits

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- Automotive product qualification in accordance with AEC-Q100 (Grade 1)
  - ◆ Specified from  $-40^{\circ}\text{C}$  to  $+85^{\circ}\text{C}$  and from  $-40^{\circ}\text{C}$  to  $+125^{\circ}\text{C}$
- 5 V tolerant inputs/outputs for interfacing with 5 V logic
- Wide supply voltage range from 2.3 V to 3.6 V
- CMOS low power consumption
- Direct interface with TTL levels
- Complies with JEDEC standard:
  - ◆ JESD8-7A (1.65 V to 1.95 V)
  - ◆ JESD8-5A (2.3 V to 2.7 V)
  - ◆ JESD8-C/JESD36 (2.7 V to 3.6 V)
- ESD protection:
  - ◆ MIL-STD-883, method 3015 exceeds 2000 V
  - ◆ HBM JESD22-A114F exceeds 2000 V
  - ◆ MM JESD22-A115-A exceeds 200 V ( $C = 200\text{ pF}$ ,  $R = 0\ \Omega$ )
- Multiple package options

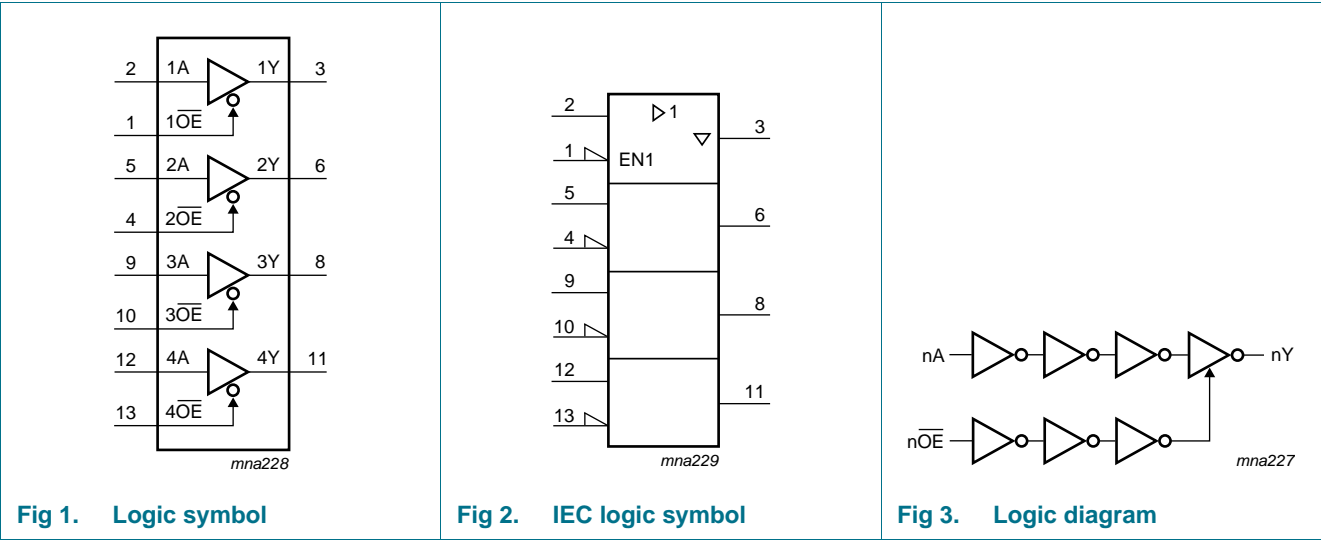


3. Ordering information

Table 1. Ordering information

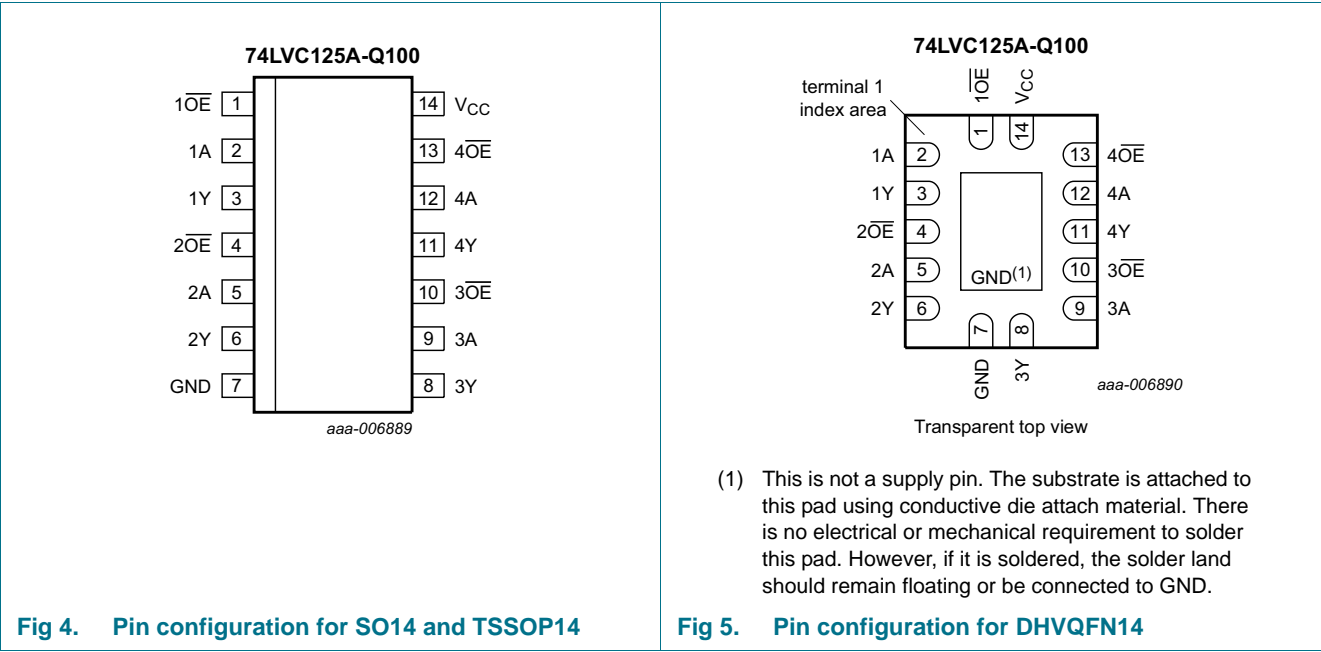
Type number	Package			Version
	Temperature range	Name	Description	
74LVC125AD-Q100	−40 °C to +125 °C	SO14	plastic small outline package; 14 leads; body width 3.9 mm; body thickness 1.47 mm	SOT108-1
74LVC125APW-Q100	−40 °C to +125 °C	TSSOP14	plastic thin shrink small outline package; 14 leads; body width 4.4 mm	SOT402-1
74LVC125ABQ-Q100	−40 °C to +125 °C	DHVQFN14	plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 14 terminals; body 2.5 × 3 × 0.85 mm	SOT762-1

4. Functional diagram



5. Pinning information

5.1 Pinning



5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
1OE, 2OE, 3OE, 4OE	1, 4, 10, 13	data enable input (active LOW)
1A, 2A, 3A, 4A	2, 5, 9, 12	data input
1Y, 2Y, 3Y, 4Y	3, 6, 8, 11	data output
GND	7	ground (0 V)
VCC	14	supply voltage

6. Functional description

Table 3. Function selection<sup>[1]</sup>

Inputs		Output
nOE	nA	nY
L	L	L
L	H	H
H	X	Z

[1] H = HIGH voltage level; L = LOW voltage level; X = don't care; Z = high-impedance OFF-state

## 7. Limiting values

**Table 4. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CC}$	supply voltage		-0.5	+6.5	V
$I_{IK}$	input clamping current	$V_I < 0$ V	-50	-	mA
$V_I$	input voltage		[1] -0.5	+6.5	V
$I_{OK}$	output clamping current	$V_O > V_{CC}$ or $V_O < 0$ V	-	$\pm 50$	mA
$V_O$	output voltage	output HIGH or LOW-state	[2] -0.5	$V_{CC} + 0.5$	V
		output 3-state	[2] -0.5	+6.5	V
$I_O$	output current	$V_O = 0$ V to $V_{CC}$	-	$\pm 50$	mA
$I_{CC}$	supply current		-	100	mA
$I_{GND}$	ground current		-100	-	mA
$P_{tot}$	total power dissipation	$T_{amb} = -40$ °C to +125 °C	[3] -	500	mW
$T_{stg}$	storage temperature		-65	+150	°C

[1] The minimum input voltage ratings may be exceeded if the input current ratings are observed.

[2] The output voltage ratings may be exceeded if the output current ratings are observed.

[3] For SO14 packages: above 70 °C derate linearly with 8 mW/K.  
 For TSSOP14 packages: above 60 °C derate linearly with 5.5 mW/K.  
 For DHVQFN14 packages: above 60 °C derate linearly with 4.5 mW/K.

## 8. Recommended operating conditions

**Table 5. Recommended operating conditions**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{CC}$	supply voltage		1.65	-	3.6	V
		functional	1.2	-	-	V
$V_I$	input voltage		0	-	5.5	V
$V_O$	output voltage	output HIGH or LOW state	0	-	$V_{CC}$	V
		output 3-state	0	-	5.5	V
$T_{amb}$	ambient temperature		-40	-	+125	°C
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{CC} = 2.3$ V to 2.7 V	0	-	20	ns/V
		$V_{CC} = 2.7$ V to 3.6 V	0	-	10	ns/V

## 9. Static characteristics

**Table 6. Static characteristics**

At recommended operating conditions. Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	–40 °C to +85 °C			–40 °C to +125 °C		Unit
			Min	Typ <sup>[1]</sup>	Max	Min	Max	
V <sub>IH</sub>	HIGH-level input voltage	V <sub>CC</sub> = 1.2 V	1.08	-	-	1.08	-	V
		V <sub>CC</sub> = 1.65 V to 1.95 V	0.65 × V <sub>CC</sub>	-	-	0.65 × V <sub>CC</sub>	-	V
		V <sub>CC</sub> = 2.3 V to 2.7 V	1.7	-	-	1.7	-	V
		V <sub>CC</sub> = 2.7 V to 3.6 V	2.0	-	-	2.0	-	V
V <sub>IL</sub>	LOW-level input voltage	V <sub>CC</sub> = 1.2 V	-	-	0.12	-	0.12	V
		V <sub>CC</sub> = 1.65 V to 1.95 V	-	-	0.35 × V <sub>CC</sub>	-	0.35 × V <sub>CC</sub>	V
		V <sub>CC</sub> = 2.3 V to 2.7 V	-	-	0.7	-	0.7	V
		V <sub>CC</sub> = 2.7 V to 3.6 V	-	-	0.8	-	0.8	V
V <sub>OH</sub>	HIGH-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>						
		I <sub>O</sub> = –100 µA; V <sub>CC</sub> = 1.65 V to 3.6 V	V <sub>CC</sub> – 0.2	-	-	V <sub>CC</sub> – 0.3	-	V
		I <sub>O</sub> = –4 mA; V <sub>CC</sub> = 1.65 V	1.2	-	-	1.05	-	V
		I <sub>O</sub> = –8 mA; V <sub>CC</sub> = 2.3 V	1.8	-	-	1.65	-	V
		I <sub>O</sub> = –12 mA; V <sub>CC</sub> = 2.7 V	2.2	-	-	2.05	-	V
		I <sub>O</sub> = –18 mA; V <sub>CC</sub> = 3.0 V	2.4	-	-	2.25	-	V
		I <sub>O</sub> = –24 mA; V <sub>CC</sub> = 3.0 V	2.2	-	-	2.0	-	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>						
		I <sub>O</sub> = 100 µA; V <sub>CC</sub> = 1.65 V to 3.6 V	-	-	0.2	-	0.3	V
		I <sub>O</sub> = 4 mA; V <sub>CC</sub> = 1.65 V	-	-	0.45	-	0.65	V
		I <sub>O</sub> = 8 mA; V <sub>CC</sub> = 2.3 V	-	-	0.6	-	0.8	V
		I <sub>O</sub> = 12 mA; V <sub>CC</sub> = 2.7 V	-	-	0.4	-	0.6	V
		I <sub>O</sub> = 24 mA; V <sub>CC</sub> = 3.0 V	-	-	0.55	-	0.8	V
I <sub>I</sub>	input leakage current	V <sub>CC</sub> = 3.6 V; V <sub>I</sub> = 5.5 V or GND	-	±0.1	±5	-	±20	µA
I <sub>OZ</sub>	OFF-state output current	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>CC</sub> = 3.6 V; V <sub>O</sub> = 5.5 V or GND	-	±0.1	±5	-	±20	µA
I <sub>OFF</sub>	power-off leakage current	V <sub>CC</sub> = 0.0 V; V <sub>I</sub> or V <sub>O</sub> = 5.5 V	-	±0.1	±10	-	±20	µA
I <sub>CC</sub>	supply current	V <sub>CC</sub> = 3.6 V; V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0 A	-	0.1	10	-	40	µA
ΔI <sub>CC</sub>	additional supply current	per input pin; V <sub>I</sub> = V <sub>CC</sub> – 0.6 V; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 2.7 V to 3.6 V	-	5	500	-	5000	µA
C <sub>I</sub>	input capacitance	V <sub>CC</sub> = 0 V to 3.6 V; V <sub>I</sub> = GND to V <sub>CC</sub>	-	4.0	-	-	-	pF

[1] All typical values are measured at V<sub>CC</sub> = 3.3 V (unless stated otherwise) and T<sub>amb</sub> = 25 °C.

## 10. Dynamic characteristics

**Table 7. Dynamic characteristics**

Voltages are referenced to GND (ground = 0 V). For test circuit see [Figure 8](#).

Symbol	Parameter	Conditions	–40 °C to +85 °C			–40 °C to +125 °C		Unit
			Min	Typ <sup>[1]</sup>	Max	Min	Max	
t <sub>pd</sub>	propagation delay	nA to nY; see <a href="#">Figure 6</a> <sup>[2]</sup>						
		V <sub>CC</sub> = 1.2 V	-	12.0	-	-	-	ns
		V <sub>CC</sub> = 1.65 V to 1.95 V	1.5	5.4	11.0	1.5	12.8	ns
		V <sub>CC</sub> = 2.3 V to 2.7 V	1.0	2.9	5.7	1.0	6.7	ns
		V <sub>CC</sub> = 2.7 V	1.5	2.8	5.5	1.5	7.0	ns
		V <sub>CC</sub> = 3.0 V to 3.6 V	1.0	2.5	4.8	1.0	6.0	ns
t <sub>en</sub>	enable time	n $\overline{\text{OE}}$ to nY; see <a href="#">Figure 7</a> <sup>[2]</sup>						
		V <sub>CC</sub> = 1.2 V	-	16.0	-	-	-	ns
		V <sub>CC</sub> = 1.65 V to 1.95 V	1.0	5.0	12.2	1.0	14.2	ns
		V <sub>CC</sub> = 2.3 V to 2.7 V	0.5	2.9	6.8	0.5	7.9	ns
		V <sub>CC</sub> = 2.7 V	1.5	3.1	6.6	1.5	8.5	ns
		V <sub>CC</sub> = 3.0 V to 3.6 V	1.0	2.3	5.4	1.0	7.0	ns
t <sub>dis</sub>	disable time	n $\overline{\text{OE}}$ to nY; see <a href="#">Figure 7</a> <sup>[2]</sup>						
		V <sub>CC</sub> = 1.2 V	-	7.0	-	-	-	ns
		V <sub>CC</sub> = 1.65 V to 1.95 V	2.2	4.6	7.5	2.2	8.7	ns
		V <sub>CC</sub> = 2.3 V to 2.7 V	0.5	2.6	4.2	0.5	5.0	ns
		V <sub>CC</sub> = 2.7 V	1.5	3.1	5.0	1.5	6.5	ns
		V <sub>CC</sub> = 3.0 V to 3.6 V	1.0	3.2	4.6	1.0	6.0	ns
t <sub>sk(o)</sub>	output skew time	V <sub>CC</sub> = 3.0 V to 3.6 V <sup>[3]</sup>	-	-	1.0	-	1.5	ns
C <sub>PD</sub>	power dissipation capacitance	per buffer; V <sub>I</sub> = GND to V <sub>CC</sub> <sup>[4]</sup>						
		V <sub>CC</sub> = 1.65 V to 1.95 V	-	6.0	-	-	-	pF
		V <sub>CC</sub> = 2.3 V to 2.7 V	-	9.4	-	-	-	pF
		V <sub>CC</sub> = 3.0 V to 3.6 V	-	12.4	-	-	-	pF

[1] Typical values are measured at T<sub>amb</sub> = 25 °C and V<sub>CC</sub> = 1.2 V, 1.8 V, 2.5 V, 2.7 V, and 3.3 V respectively.

[2] t<sub>pd</sub> is the same as t<sub>PLH</sub> and t<sub>PHL</sub>.

t<sub>en</sub> is the same as t<sub>PZL</sub> and t<sub>PZH</sub>.

t<sub>dis</sub> is the same as t<sub>PLZ</sub> and t<sub>PHZ</sub>.

[3] Skew between any two outputs of the same package switching in the same direction. This parameter is guaranteed by design.

[4] C<sub>PD</sub> is used to determine the dynamic power dissipation (P<sub>D</sub> in  $\mu$ W).

$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o)$  where:

f<sub>i</sub> = input frequency in MHz; f<sub>o</sub> = output frequency in MHz

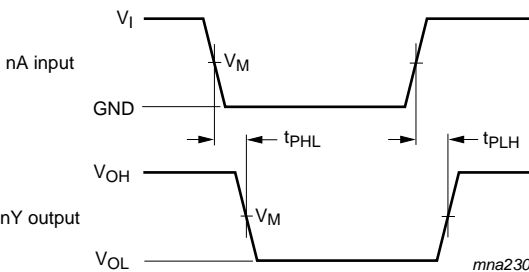
C<sub>L</sub> = output load capacitance in pF

V<sub>CC</sub> = supply voltage in Volts

N = number of inputs switching

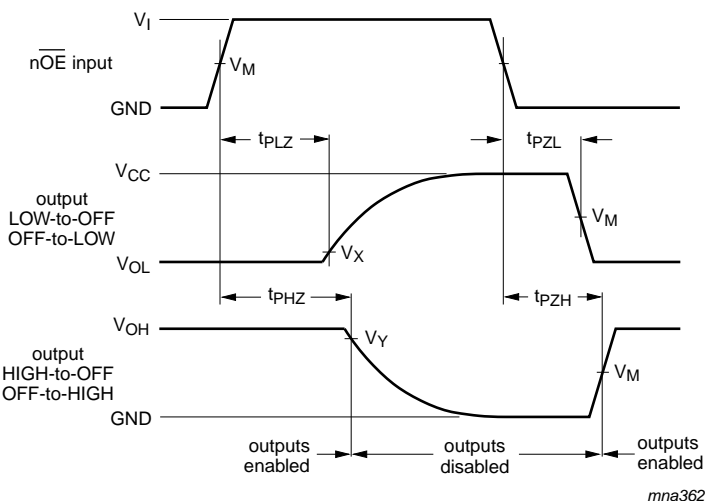
$\Sigma(C_L \times V_{CC}^2 \times f_o)$  = sum of the outputs.

11. AC waveforms



Measurement points are given in [Table 8](#).  
 $V_{OL}$  and  $V_{OH}$  are typical output voltage levels that occur with the output load.

**Fig 6. The input nA to output nY propagation delays**

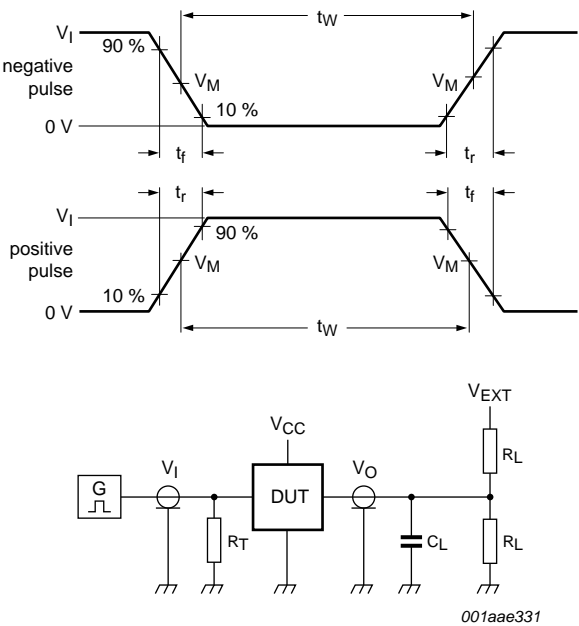


Measurement points are given in [Table 8](#).  
 $V_{OL}$  and  $V_{OH}$  are typical output voltage levels that occur with the output load.

**Fig 7. 3-state enable and disable times**

**Table 8. Measurement points**

Supply voltage	Input		Output
$V_{CC}$	$V_I$	$V_M$	$V_M$
1.2 V	$V_{CC}$	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$
1.65 V to 1.95 V	$V_{CC}$	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$
2.3 V to 2.7 V	$V_{CC}$	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$
2.7 V	2.7 V	1.5 V	1.5 V
3.0 V to 3.6 V	2.7 V	1.5 V	1.5 V



Test data is given in [Table 9](#).  
Definitions for test circuit:  
 $R_L$  = Load resistance.  
 $C_L$  = Load capacitance including jig and probe capacitance.  
 $R_T$  = Termination resistance should be equal to output impedance  $Z_o$  of the pulse generator.  
 $V_{EXT}$  = External voltage for measuring switching times.

Fig 8. Test circuit for measuring switching times

Table 9. Test data

Supply voltage	Input		Load		V <sub>EXT</sub>		
	V <sub>I</sub>	t <sub>r</sub> , t <sub>f</sub>	C <sub>L</sub>	R <sub>L</sub>	t <sub>PLH</sub> , t <sub>PHL</sub>	t <sub>PLZ</sub> , t <sub>PZL</sub>	t <sub>PHZ</sub> , t <sub>PZH</sub>
1.2 V	V <sub>CC</sub>	≤ 2 ns	30 pF	1 kΩ	open	2 × V <sub>CC</sub>	GND
1.65 V to 1.95 V	V <sub>CC</sub>	≤ 2 ns	30 pF	1 kΩ	open	2 × V <sub>CC</sub>	GND
2.3 V to 2.7 V	V <sub>CC</sub>	≤ 2 ns	30 pF	500 Ω	open	2 × V <sub>CC</sub>	GND
2.7 V	2.7 V	≤ 2.5 ns	50 pF	500 Ω	open	2 × V <sub>CC</sub>	GND
3.0 V to 3.6 V	2.7 V	≤ 2.5 ns	50 pF	500 Ω	open	2 × V <sub>CC</sub>	GND



12. Package outline

SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1

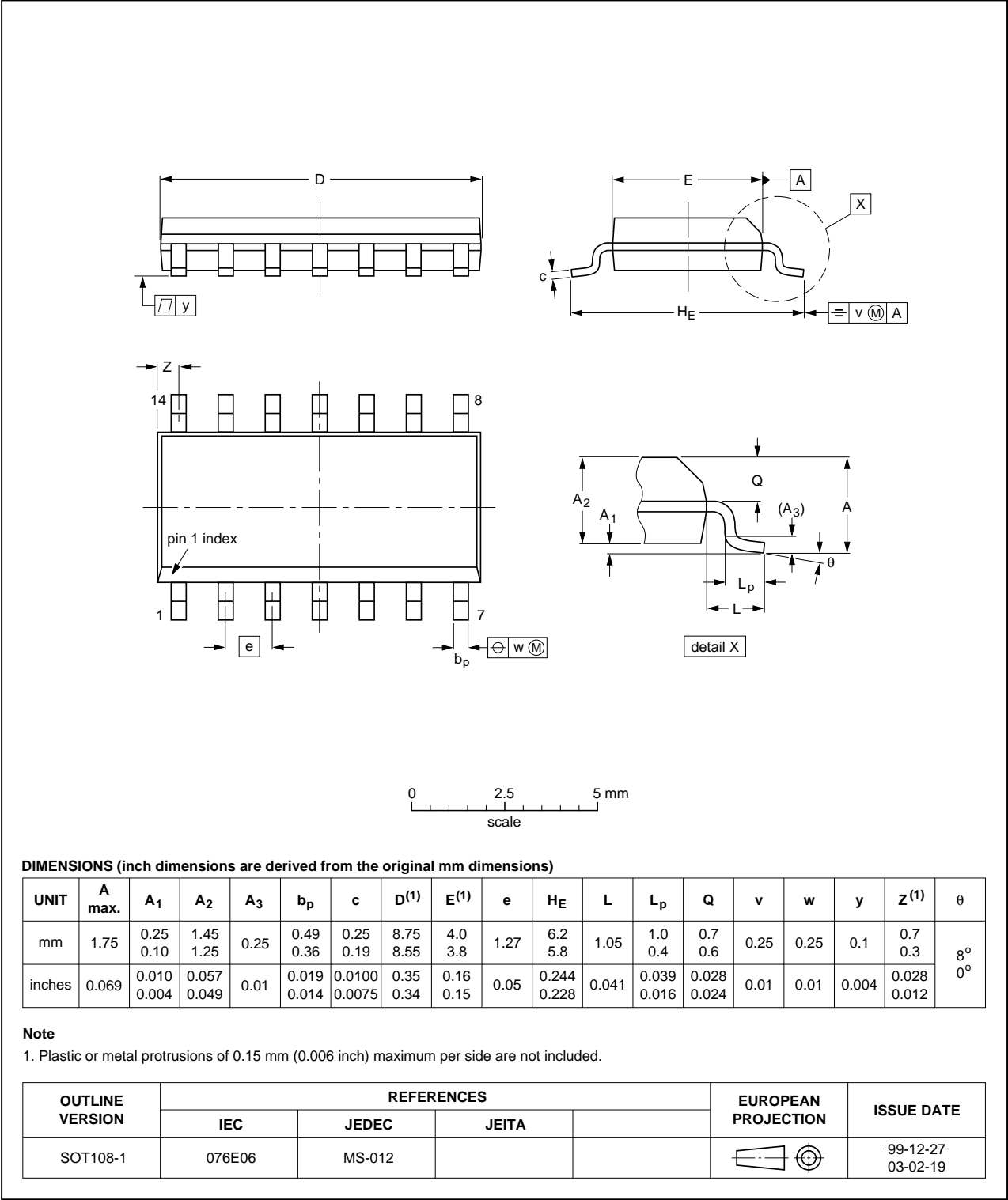


Fig 9. Package outline SOT108-1 (SO14)

TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm

SOT402-1

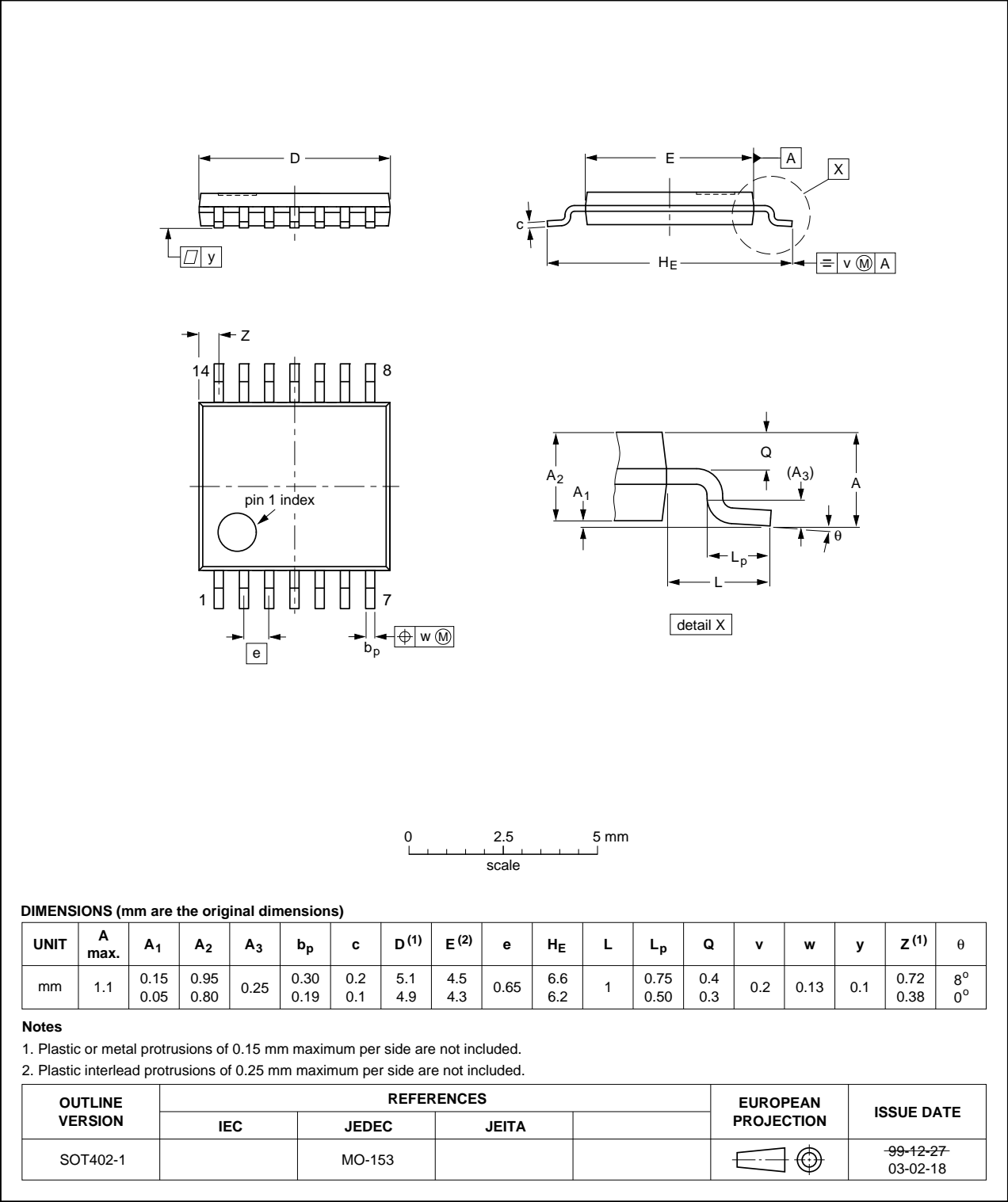


Fig 10. Package outline SOT402-1 (TSSOP14)

DHVQFN14: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads;  
14 terminals; body 2.5 x 3 x 0.85 mm SOT762-1

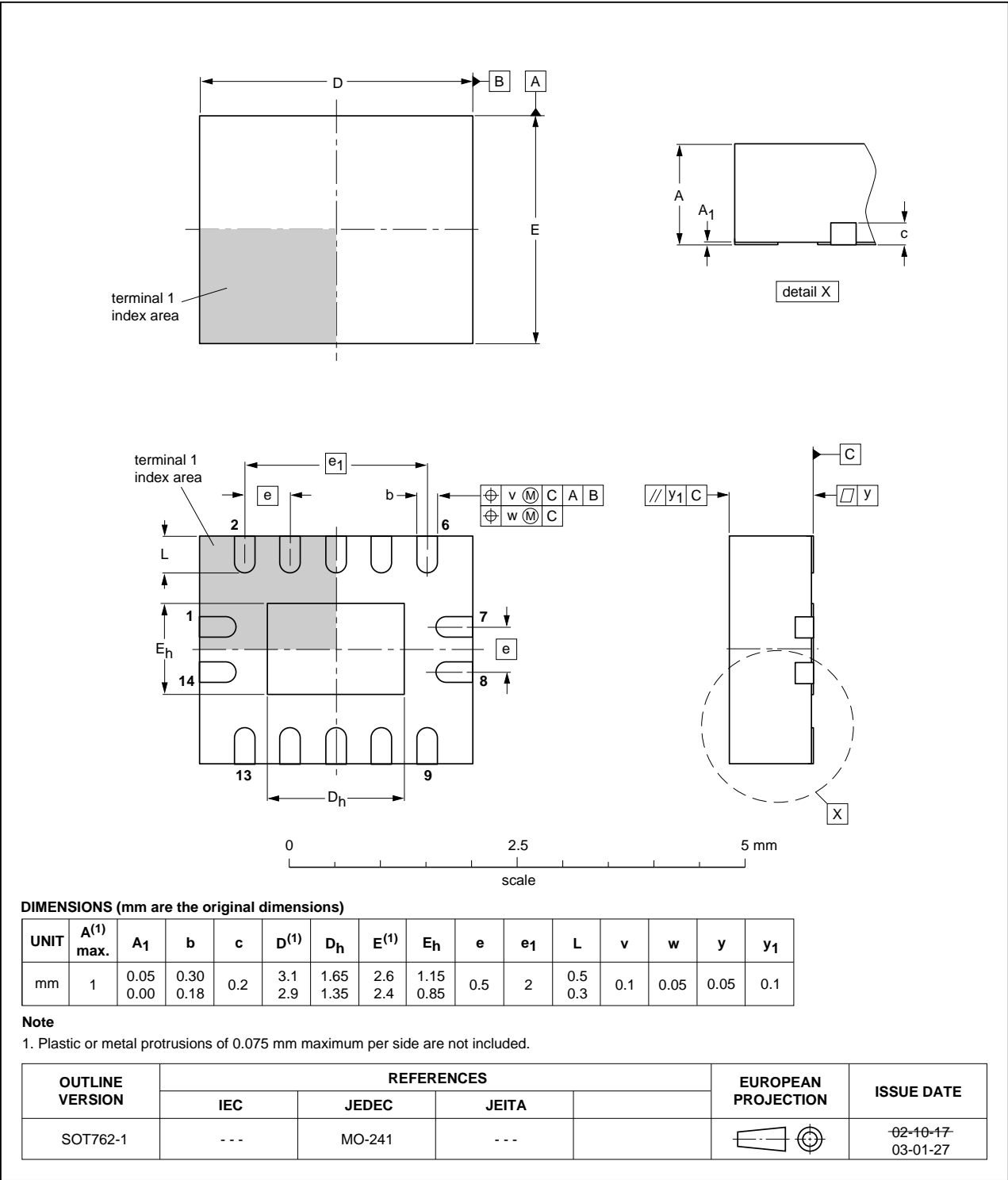


Fig 11. Package outline SOT762-1 (DHVQFN14)

## 13. Abbreviations

Table 10. Abbreviations

Acronym	Description
CDM	Charged Device Model
DUT	Device Under Test
ESD	ElectroStatic Discharge
MIL	Military
MM	Machine Model
HBM	Human Body Model
TTL	Transistor-Transistor Logic

## 14. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74LVC125A_Q100 v.1	20130404	Product data sheet	-	-

## 15. Legal information

### 15.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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Product [short] data sheet	Production	This document contains the product specification.

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